

WHAT IS CLAIMED IS:

1. A semiconductor device comprising:

5 a plurality of semiconductor elements each having
a plurality of arranged pads, the semiconductor elements
being stacked and housed in the semiconductor device; and
a power supply frame that is bar-shaped and
supplies a power voltage to at least two of the plurality
of semiconductor elements.

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2. The semiconductor device according to claim 1,
wherein the power supply frame is provided on each of the
semiconductor elements to which a power is supplied, and
the power supply frame includes frame portions placed along
15 rows of pads of the semiconductor elements and a portion
coupling the frame portions.

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3. The semiconductor device according to claim 1,
wherein when the power supply frame supplies a power to two
semiconductor elements, the power supply frame is provided
on a larger semiconductor element of the two semiconductor
elements.

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4. The semiconductor device according to claim 3,
wherein the power supply frame is placed between the rows

of the pads of the two semiconductor elements.

5. A semiconductor device comprising:

5 a plurality of semiconductor elements each having
a plurality of arranged pads, the semiconductor elements
being stacked and housed in the semiconductor device; and

a spacer inserted between the semiconductor
elements and having a electrical conductivity,

10 wherein the spacer is connected to the pads of at
least the one semiconductor element by wire bonding.